



Conference on Electronics Assembly: Soldering, Assembly & Inspection

20-22 March 2012 | Budapest, Hungary | Ramada Resort Aquaworld

This three-day event will be packed with informative workshops, exhibits and a comprehensive technical conference that will provide all attendees with a competitive edge in eastern Europe's fast-growing electronics interconnect market.

No company — big or small — can afford to miss the valuable information exchange, discussions and networking that will take place. Register today at www.ipc.org/budapest-conference

Agenda:

Tuesday, 20 March, 2012: Half-Day Workshops

- 8:00 Registration, Networking Breakfast
- 9:00 **Workshop 1: Why Are My Solder Joints Not Perfect? Methods for Analyzing and Recommended Actions to Solve the Problem and to Ensure That It Will Not Happen Again**
Lars Wallin, IPC European Representative
- 9:00 **Workshop 2: Cleaning Printed Circuit Assemblies, Design & Process Control Workshop**
Bob Willis, ASKbobwillis.com
- 13:30 **Workshop 3: Steps for Practical Failure Analysis**
Bob Willis, ASKbobwillis.com
- 13:30 **Workshop 4: How Can Flex and Flex Rigid Boards Be a Technical and Economic Success in Electronic Products? A Detailed Survey of Economic Calculations, Design Rules, Choice of Material and Production Parameters**
Lars Wallin, IPC European Representative

Wednesday, 21 March, 2012: Exhibits & Conference Sessions

- 7:30 Registration, Networking Breakfast
- 8:30 **Issues Which Impact the Quality and Reliability of an Assembled Board**
Lars Wallin, IPC European Representative
- 9:00 **Which PCB Surface Finish is Best and What Are the Common Failure Modes During Assembly & Operation**
Bob Willis, ASKbobwillis.com
- 9:45 Break, exhibits
- 10:30 **Low Melting Point Lead-Free Soldering Materials to Eliminate Board Assembly Process Steps While Avoiding Design Changes**
Corne Hopperbrouwers, European Automotive Technology Manager, Alpha
- 11:10 **Reliability of Fluxes Used in Selective Soldering Processes**
Han Raetzen, Area Sales & Support Manager, Balver Zinn
- 11:50 **Cost Effective Soldering with Micro Alloyed Solder Reducing Dross**
Jens Gruse, Application Engineering, Stannol GmbH
- 12:30 Networking Lunch
- 13:30 **Challenges with Step Stencils in the Printing Process**
Carmina Lantsch, Sales, LaserJob
- 14:10 **Stencil Technology — State of the Art?**
Lothar Pietrzak, Director Sales/Marketing, Christian Koenen GmbH
- 14:50 Break, Exhibits
- 15:35 **Will Global Environmental Regulations and Corporate Responsibility Impact Product Reliability?**
Tony Hilvers, Vice President of Industry Programs, IPC

- 16:15 **Keynote Address: Reliability Issues for Advanced Electronic Products**
Dr. Dongkai Shangguan, Vice President of Advanced Technology, Flextronics

- 17:00 Networking Reception, Exhibits

Thursday, 22 March 2012: Exhibits & Conference Sessions

- 7:30 Networking breakfast, exhibits
- 8:30 **The Closed Loop Project Between Screen Printer and SPI by PARMi**
Woong Jang, Global Sales, Parmi
- 9:10 **Cleaning Highly Dense Circuit Assemblies**
Serge Tuerlings, Technical Manager Europe, Kyzen
- 9:50 Break, Exhibits
- 10:35 **Cleaning Electronic Assemblies in a No-Clean World**
Mike Nelson, Managing Director, ETEK Europe
- 11:15 **Next Generation Board Repair**
Tom Bex, Area Sales Manager, Soldering Systems & Printing Machines, ERSA
- 11:55 **Depaneling Printed Circuit Boards — Tools and Methods for Safely Singulating Panelized PCBs**
Klaus Heimann, President, FKN Systek
- 12:35 Networking Lunch
- 13:35 **Inline Automation Inspection — Don't Find Defects Only; Control Your Process Quality! Use the Information Which SPI, AOI and AXI Provide to Observe Quality Features and to Take Corrective Action Before Defects Occur!**
Michael Muegge, Sales Engineer, Viscom AG
- 14:15 **Technology Breakthrough in 2-D X-Ray**
Keith Bryant, Global Sales Director X-ray Systems, Nordson Dage
- 14:55 Break, Exhibits
- 15:10 **3-D AOI Technology**
Harald Eppinger, European Sales Manager, Koh Young Europe
- 15:50 **Failure Analysis — Reduce Your Costs with a Specialized, Independent Laboratory**
Peter Gordon, Managing Director, EFI-labs Europe
- 16:30 **Optimization of Cleaning PCB Assemblies and Stencil Through Process Examination**
Vladimír Sitko (PBT), ELAS Kft
- 17:10 Adjourn





For more information and to register, visit www.ipc.org/budapest-conference



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FREE

Keynote Speaker:



Dongkai Shangguan
Ph.D., MBA,
IEEE Fellow

21 March, 16:15

Dr. Shangguan has published two books, more than 250 papers and articles, and has given numerous technical presentations. He has more than 20 U.S. and international patents issued and a number of U.S. and international patents pending.

Registration

To register, go to www.ipc.org/budapest-conference

	IPC Member Price	Standard Price
Workshop (each):	170 EUR	195 EUR
Conference:	125 EUR	150 EUR
Conference Package: <i>(includes 2 workshops + conference)</i>	375 EUR	450 EUR

Hotel and Meeting Location

This event will be held at:

Ramada Resort Aquaworld
1044 Budapest
Ives utca 16, Hungary
06 1 231-3600

Reservations should be made directly with the Ramada Resort Aquaworld. Please mention you are with IPC to receive a discounted rate per night. The IPC rate of 95 EUR/ single and 115 EUR/ double is available until all rooms in the IPC block are booked or until 27 February 2012.

Sponsors:



Media Sponsors:



Sponsorship and Tabletop Exhibits:

Sponsorships and tabletops are available. Reach the event attendees and the thousands of people who will receive promotional materials. For more information, contact Maria Labriola, trade show sales manager, at +1 847-597-2866 or MariaLabriola@ipc.org.

Contact Information:

For more information on the IPC Conference on Electronics Assembly, contact Fathima Hussain, manager, Industry Programs, at FathimaHussain@ipc.org.